FIXED ABRASIVE CMP PAD WITH BUILT-IN ADDITIVES

ABTRACT OF THE DISCLOSURE

This invention discloses fixed abrasive chemical mechanical polishing pads, wherein the pad itself comprises at least one material selected from the group consisting of oxidants, wetting agents and other additives normally delivered via a polishing slurry, which assist in the polishing effectiveness of the pad. The improved polishing pad provides both the benefit of a fixed abrasive and the benefits of slurry based polishing systems.